Connector Datasheet

PT06M00005R1

Nano SIM WITH TRAY

PUSH PUSH TYPE H=1.47mm

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Version	Changed Reason	Changed by	Date
01	Original version	Hyde	20191030

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TECHNICAL INFORMATION

MATERIALS

- Materials used in the construction of product shall be as specified on the applicable product drawing

ELECTRICAL PERFORMANCE

Voltage Rating : 10V DC

Current Rating : 0.5Amps Max

Contact Resistance (signal) : 100mΩ Initial (140mΩ After Test) Max.

Insulation Resistance : 500MΩ Min. at 500VDC .

Dielectric Withstanding Voltage : 250VAC/Minute .

Operating Temperature : -25° C~+85° C

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MECHANICAL PERFORMANCE

- Card Insertion Force : Initial value:1.0Kg Max.
- Card Release Force : Initial value: 0.1Kgf Max.
- Contact Retention Force : Male: 300gf / pin Min.
- Durability : 5000 cycles

PACKING

- Reel packing

TEST REQUIREMENTS AND PROCEDURES SUMMARY

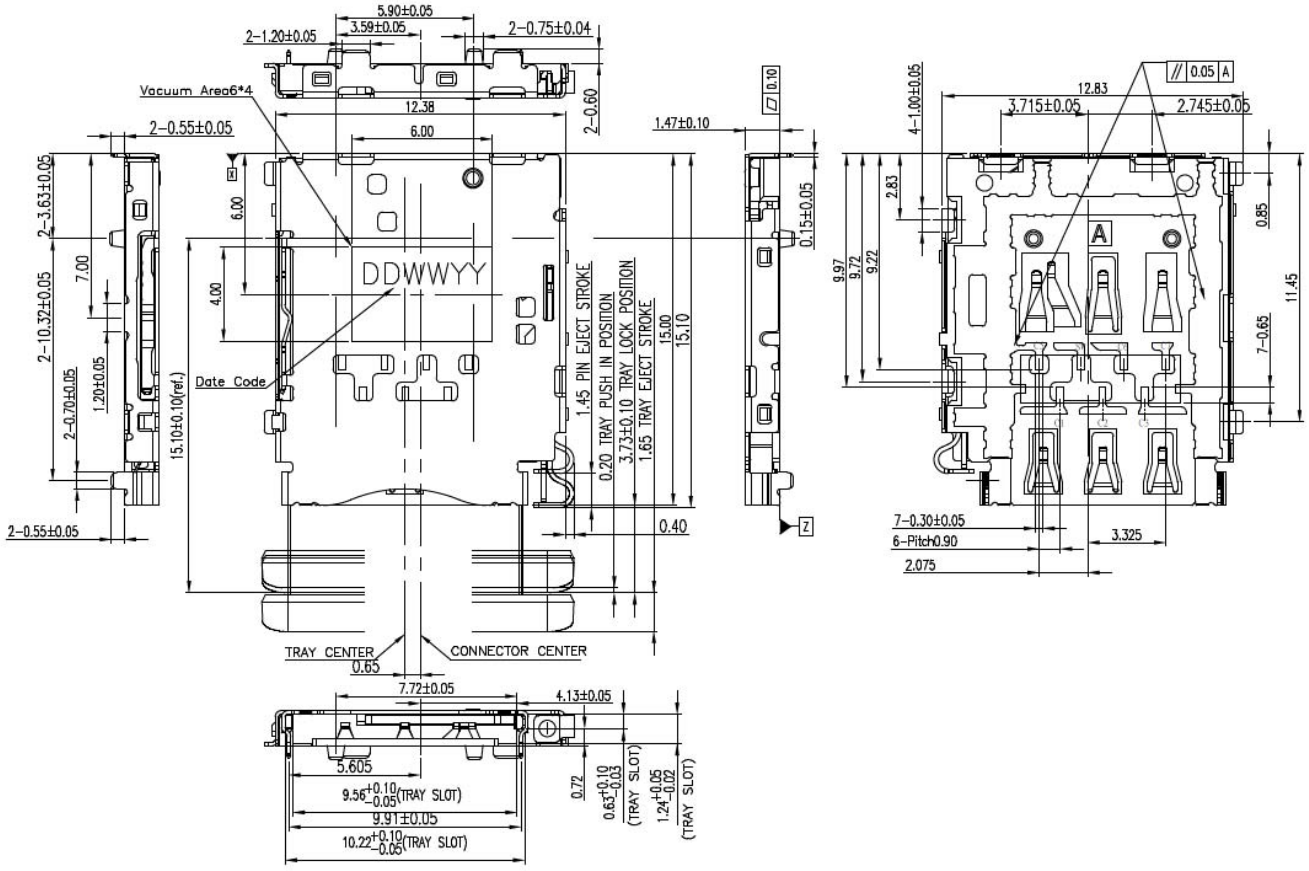
Test Description	Requirement	PROCEDURED
Examination of product	Meets requirements of product drawing and Specification.	Visual inspection No physical damage
Electrical		
Low Level Contact Resistance	Connector contacts: Initial: 100mΩ max After test: 140mΩ max R 40mΩ max Detection switch contact Initial: 500mΩ max After test:540mΩ max	Mate dummy card, measure by dry circuit, 20mV max,10mA max. (EIA 364-23)
Insulation Resistance	1000MΩ Min. at 500V DC / 2min.	EIA-364-21-E
Dielectric Withstanding Voltage	No breakdown at 500V RMS	EIA-364-20-E
MECHANICAL		
Durability	5000 time Appearance: No damage contact.Resistance:150mΩMax. Measuring by dummy card	Insertion and extraction are repeated 7000 cycles with the actually card at the speed rate of 400~600 cycles/hour. Exchange the actually card every 2000 cycles (EIA364-09)
Card Insertion Force	Initial value:1.0Kg Max.	Speed 25±3mm/minute
Card Release Force	Initial value: 1.0Kgf Max.	Speed 25±3mm/minute
Vibration	Appearance: no damage. Discontinuity: 1 microsecond Max.	Mate dummy card and place them on the vibrator, then apply the following vibration. Then it shall be measured. In accordance with EIA-364-28 Frequency :10Hz→55Hz→10Hz. Direction : Three mutually perpendicular directions. Total amplitude : 1.50mm Sweep duration : 2 hours for each direction, a total of 6 hours.
Mechanical Shock	Appearance: no damage. Discontinuity: 1 microsecond Max.	Mate dummy card and place them on the vibrator, then apply the following vibration. Then it shall be measured. In accordance with EIA-364-28 Frequency :10Hz→55Hz→10Hz. Direction : Three mutually perpendicular directions. Total amplitude : 1.50mm

		Sweep duration : 2 hours for each direction, a total of 6 hours.
ENVIRONMENTAL		
Humidity	Meets requirements of product drawing and electrical specification.	EIA-364-31C method Ⅱ Condition A
Salt spray	Meets requirements of product drawing and electrical specification.	Mate dummy card and expose them to the following environment in accordance with EIA-364-26. Temperature ： 35± 2℃ Relative Humidity：95～98%RH Salt water density：5+/-1 % (by weight) Duration ： 24 hours
Low Temperature	Meets requirements of product drawing and electrical specification	The connector housing shall be store at temperature of -25 ± 3°C for 48hours
Dry heat	Meets requirements of product drawing and electrical specification	The connector housing shall be store at temperature of 85 ± 2°C for 96hours EIA-364-17C
Thermal Cycling	No abnormality	Cycle the connector between -15℃ +/-3 ℃ and 85℃+/-3℃. Ramps should be 1 ℃ min. per minute, and dwell times should ensure the contacts reach the temperature extremes (5 minutes min.). Humidity is not controlled. Perform 100 such cycles. Follow EIA-364-110
PHYSICAL		
Solderability	The test area shall be covered more than 95% of immersed area with flash solder	Solder Temperature: 240℃ ± 5℃ Immersion Period: 3 ± 0.5sec.
Resistance to Soldering Heat	1. Without deformation of case or excessive loosen. 2. Electrical characteristics shall be satisfied	Place the connector on the P.C. Board, then immerse the solder pin up to the surface of the board in the solder bath at 260℃ ± 5℃ for 5 sec.(Included 245℃ ± 5℃ for 10 sec.)

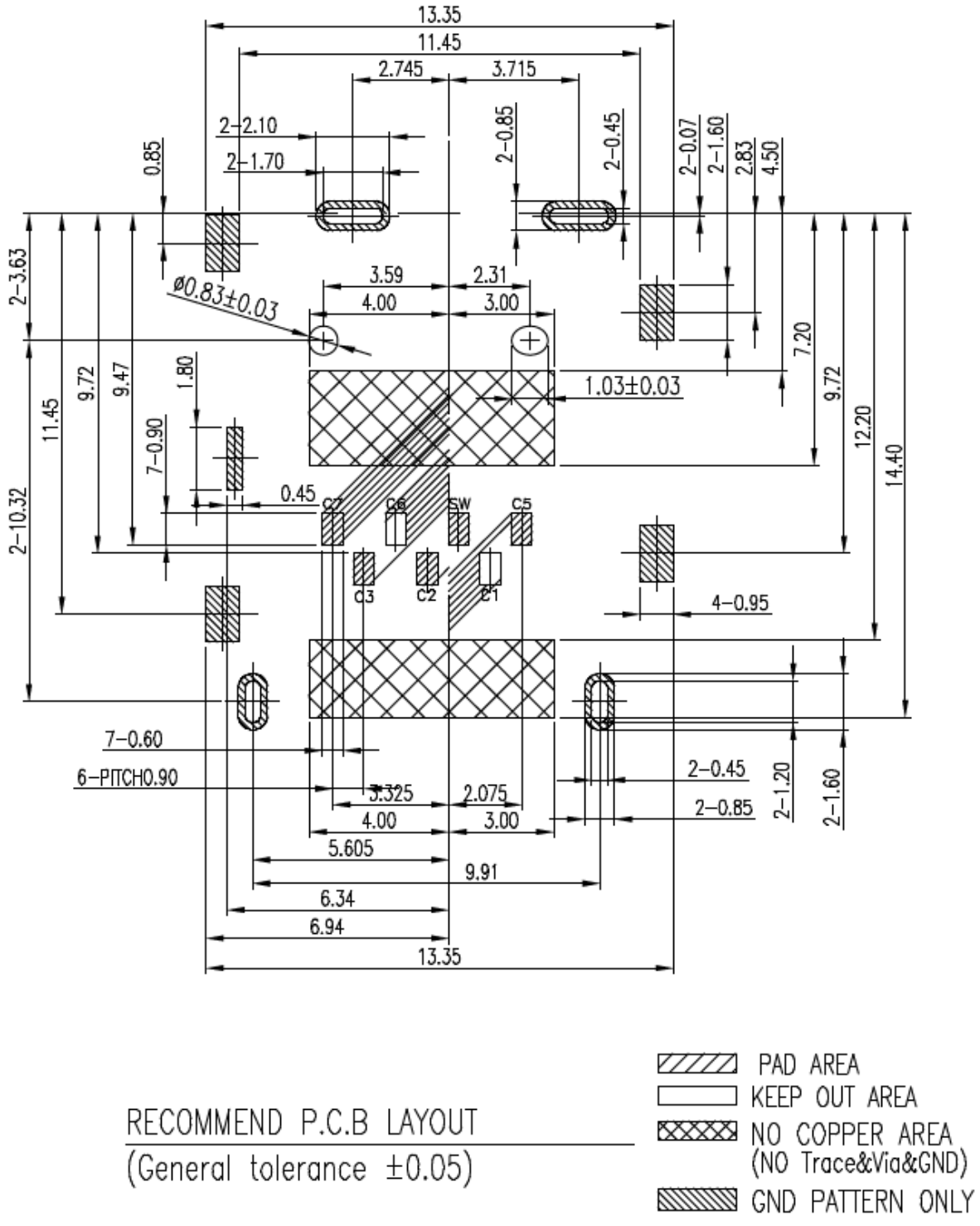
Figure 1

NOTE: Shall meet visual requirements, show no physical damages.

Component Configuration and Dimensions



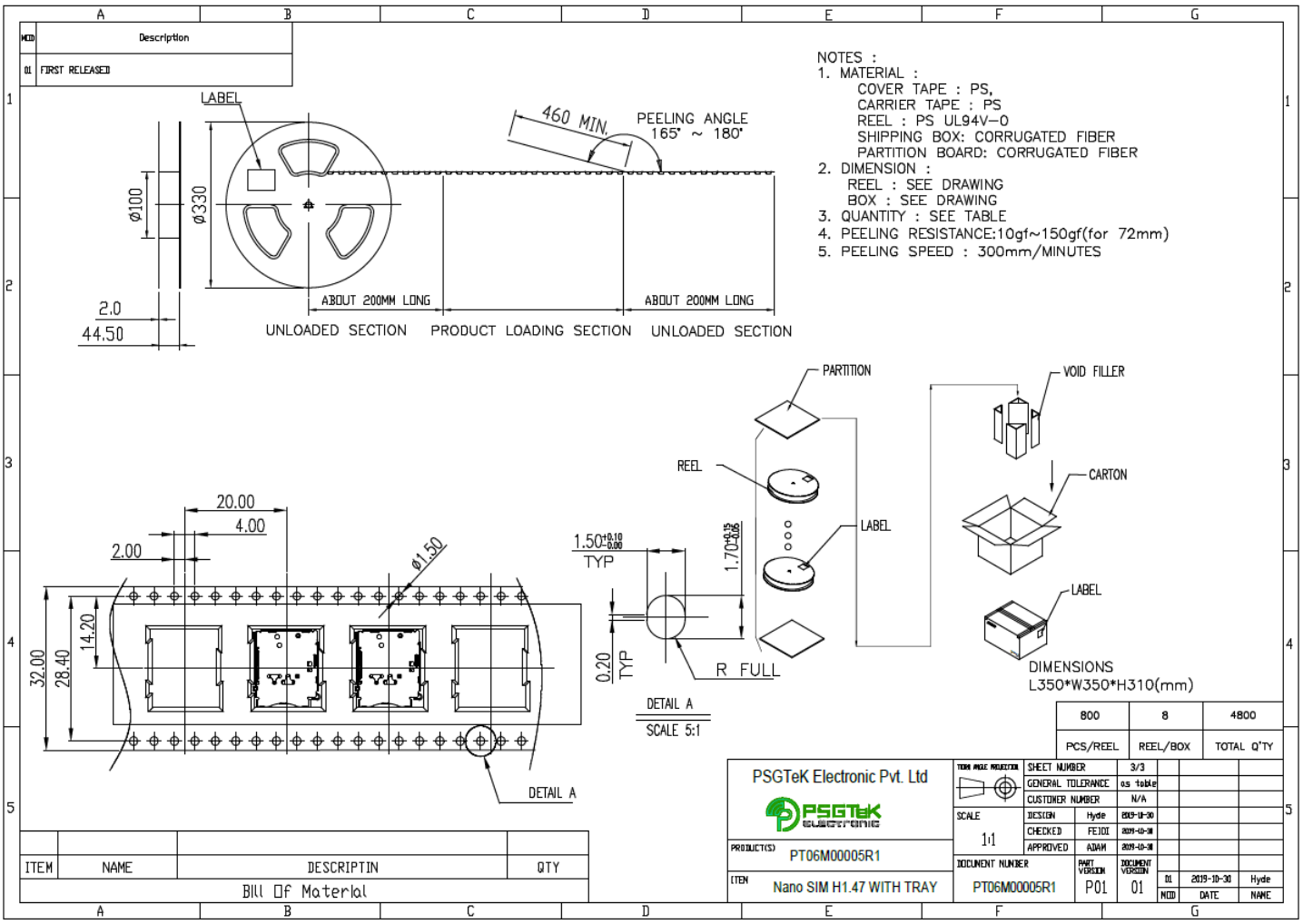
Pins assignment for PCB Layout



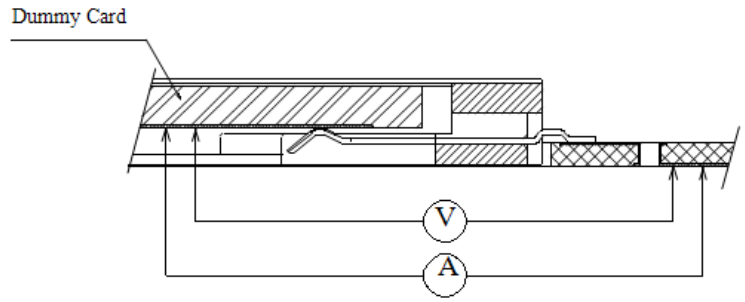
RECOMMEND P.C.B LAYOUT
(General tolerance ±0.05)

PAD AREA
KEEP OUT AREA
NO COPPER AREA
(NO Trace&Via&GND)
GND PATTERN ONLY

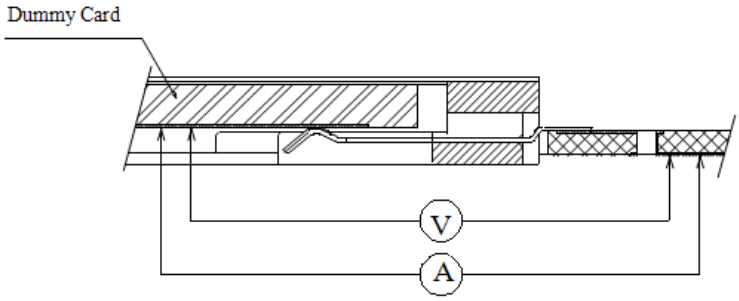
Packing drawing



Contact Resistance

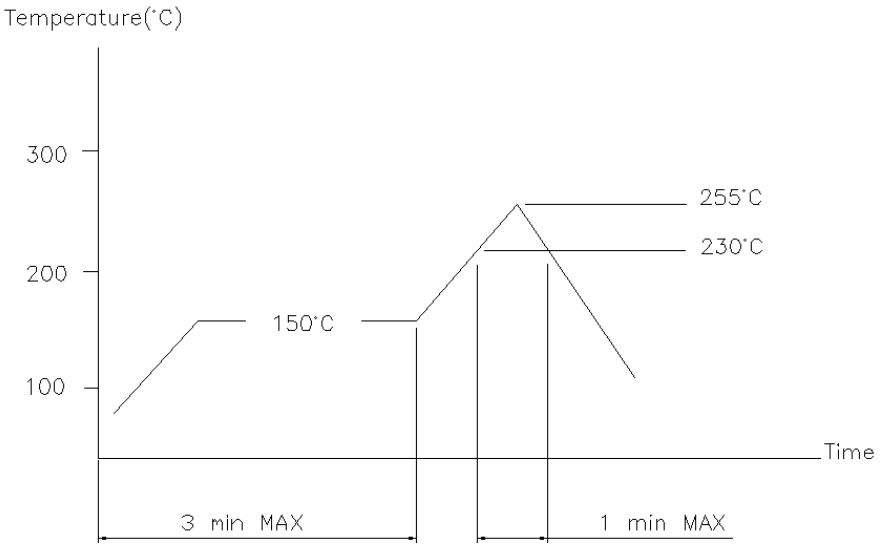


(Fig.1 Contact Resistance /)



(Fig.2 Contact Resistance /)

Resistance to flow solder heat



Note: The product specification only for standard product